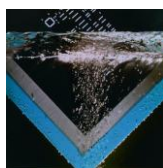


HYDRON® SC 300

Water-based stencil cleaner for the removal of solder pastes and SMT adhesives



HYDRON® SC 300 is a water-based, single-phase cleaning agent for SMT stencils. The cleaning agent reliably removes solder pastes and SMT adhesives at room temperature and does not leave any adhesive pigment residues on the surface. HYDRON® SC 300 is recommended for cleaning and rinsing and dries residue-free.

Areas of application: Stencil cleaning		Additional product information:
Solder paste (unsoldered)	++	Material Compatibility Overview
SMT or conductive adhesives	++	

++ highly recommended, best results

+ recommended

0 possible

- not recommended

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ North-China, ⑤ South-China Cleaning Process Solutions under Production Floor Conditions



Advantages compared to other cleaners:

- Excellent cleaning performance on solder pastes and SMT adhesives, does not leave any pigment residues
- Recommended for cleaning and rinsing
- Residue-free drying, does not leave any streaks on stencils
- No foaming in spray-in-air systems, neither in the cleaning nor in the rinsing section, can also be used with water rinsing
- VOC content < 20 %, therefore no subject to approval
- Excellent material compatibility with stencils
- Water-based cleaner without flash point, no explosion-proof protection required

Please refer to the Material Compatibility Overview before cleaning plastics.

Process Steps	1. Cleaning	2. Rinsing	3. Drying
Spray-in-air	HYDRON® SC 300	HYDRON® SC 300, water or DI-water*	Hot air or circulating air
Ultrasonic	HYDRON® SC 300	HYDRON® SC 300, water or DI-water*	Hot air or circulating air

* Depending on the water hardness, rinsing with regular water might be sufficient for stencil cleaning. In the case of high water hardness, lime marks may stay behind. For misprint cleaning, rinsing with DI-water is highly recommended.

Technical Data		
HYDRON® SC 300 is available as concentrate or ready-to-use solution. Please note that the information below represents HYDRON® SC 300 as a ready-to-use mixture.		
Density	(g/ccm) at 20°C	0,99
Surface tension	(mN/m) at 25°C	26,7
Boiling range	°C	98 - 229
Flash point	°C	None
pH-value	10g/l H ₂ O	Neutral
Vapor pressure	(mbar) at 20°C	approx. 20
Solubility in water		Soluble
Cleaning temperature	°C	20 - 50
Application concentration	Ready-to-use	Pure
Application concentration ¹	Concentrate	20 %

¹ HYDRON® SC 300 is recommended to be diluted in DI-water.

PRODUCT FEATURES



Extensively tested and suitable for cleaning of lead-free solder pastes



Product is free of any critical substances according to SIN & SVHC lists



100% compliance with EU guidelines (RoHS 1 & 2, WEEE)

Filter recommendation:

- To take full advantage of the bath life of HYDRON® SC 300, filtration is recommended.

Environmental, health and safety regulations:

- HYDRON® SC 300 is water-based and biodegradable.
- Rinsing with water is not necessary. This results in the elimination of water streams and water treatment processes.
- The cleaning agent is formulated free of any halogenated compounds.
- Refer to the MSDS for specific handling precautions and instructions.

Availability/Storage:

- HYDRON® SC 300 is available as ready-to-use-solution or as concentrate in 1l bottles, 5l or 25l containers and 200l drums.
- HYDRON® SC 300 is a non-hazardous material and according to EU standards does not require specific labelling.
- Store HYDRON® SC 300 in the original container at a temperature between 5 - 30°C / 41- 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.